Silicon P Channel MOS Type (U-MOSII)/Silicon Epitaxial Schottky Planar Diode

SSM5G01TU

DC-DC Converter for DSCs and Camcorders

- Co-packaged Pch MOSFET and Schottky Diode.
- Low RDS (ON) and Low VF

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-Source voltage		V _{DS}	-30	V	
Gate-Source voltag	je	V _{GSS}	GSS ±20		
Drain current	DC	۱ _D	-1.0	А	
	Pulse	I _{DP} (Note 2)	-2.0	~	
Channel temperature		P _D (Note 1)	0.5	W	
		t = 10s	0.8	vv	
Channel temperature		T _{ch}	150	°C	

Maximum Ratings (Ta = 25°C) SCHOTTKY DIODE

Characteristics	Symbol	Rating	Unit
Maximum (peak) reverse voltage	V _{RM}	25	V
Reverse voltage	V _R	20	V
Average forward current	Ι _Ο	0.5	А
Peak one cycle surge forward current (non-repetitive)	I _{FSM}	2 (50 Hz)	А
Junction temperature	Tj	125	°C

2.1 ± 0.1 1.7±0.1 1.3±0.1 2.0±0.1 0.7±0. 4 : CATHODE 1 : GATE 2 : SOURCE 5 : DRAIN 3 : ANODE UFV JEDEC JEITA ____ TOSHIBA 2-2R1A

Weight: 7 mg (typ.)

Maximum Ratings (Ta = 25°C) MOSFET, DIODE COMMON

Characteristics	Symbol	Rating	Unit
Storage temperature	T _{stg}	-55~125	°C
Operating temperature	T _{opr} (Note 3)	-40~100	°C

Note 1: Mounted on FR4 board

 $(25.4 \text{ mm} \times 25.4 \text{ mm} \times 1.6 \text{ t}, \text{ Cu pad: } 645 \text{ mm}^2)$

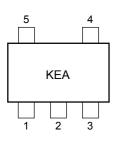
Note 2: The pulse width limited by max channel temperature.

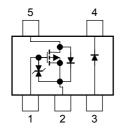
Note 3: Operating temperature limited by max channel temperature and max junction temperature.

Unit: mm

Marking

Equivalent Circuit





Handling Precaution

When handling individual devices (which are not yet mounting on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials. The Channel-to-Ambient thermal resistance R_{th} (ch-a) and the drain power dissipation PD vary according to the board material, board area, board thickness and pad area are also affected by the environment in which the

product is used. When using this device, please take heat dissipation fully into account.

90%

of

t_{on}

MOSFET

Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage current		I _{GSS}	$V_{GS}=\pm 16~V,~V_{DS}=0$	_		±1	μA	
Drain-Source breakdown voltage		V (BR) DSS	$I_D = -1 \text{ mA}, V_{GS} = 0$	-30		_	v	
		V (BR) DSX	$I_D = -1 \text{ mA}, V_{GS} = 20 \text{ V}$	-15			v	
Drain Cut-off current		I _{DSS}	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0$			-1	μA	
Gate threshold voltage		V _{th}	$V_{DS} = -5 \text{ V}, \text{ I}_{D} = -0.1 \text{ mA}$	-0.8		-1.8	V	
Forward transfer admittance		Y _{fs}	$V_{DS} = -5 \text{ V}, \text{ I}_{D} = -0.5 \text{ A}$ (Note 4)	0.5	1.0		S	
Drain-Source ON resistance		R _{DS} (ON)	$I_D = -0.5 \text{ A}, V_{GS} = -10 \text{ V}$ (Note 4)	_	0.3	0.4	Ω	
			$I_D = -0.5 \text{ A}, V_{GS} = -4 \text{ V}$ (Note 4)	_	0.6	0.8		
Input capacitance		C _{iss}	V_{DS} = -15 V, V_{GS} = 0, f = 1 MHz	_	86		pF	
Reverse transfer capacitance		C _{rss}	$V_{DS} = -15 \text{ V}, \text{ V}_{GS} = 0, \text{ f} = 1 \text{ MHz}$		14		pF	
Output capacitance		C _{oss}	V_{DS} = -15 V, V_{GS} = 0, f = 1 MHz	_	25		pF	
Switching time	Turn-on time	t _{on}	$V_{DD} = -15 \text{ V}, \text{ I}_{D} = -0.5 \text{ A}$	_	14		ns	
	Turn-off time	t _{off}	$V_{GS} = 0 \sim -4 \text{ V}, \text{ R}_{G} = 10 \Omega$	_	8.5	_		

Note 4: Pulse measurement

Switching Time Test Circuit

(a) Test circuit (b) V_{IN} 0 V 10% $V_{DD} = -15 V$ OUT $R_G=10\;\Omega$ -4 V $Duty \leq 1\%$ V_{IN}: t_r, t_f < 5 ns VDS (ON) Common source 90% 10 μs (c) V_{OUT} Ta = 25°C 10% V_{DD} V_{DD} tr

Precaution

 V_{th} can be expressed as voltage between gate and source when low operating current value is ID = $-100~\mu A$ for this product. For normal switching operation, V_{GS} (on) requires higher voltage than V_{th} and V_{GS} (off) requires lower voltage than V_{th} .

(Relationship can be established as follows: V_{GS} (off) < V_{th} < V_{GS} (on))

Please take this into consideration for using the device.

VGS recommended voltage of -2.5 V or higher to turn on this product.

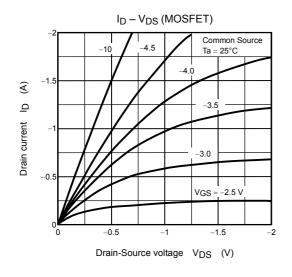
Schottky Diode

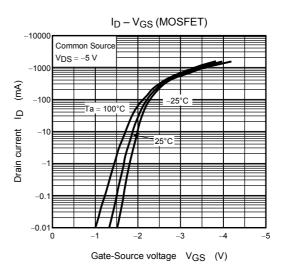
Electrical Characteristics (Ta = 25°C)

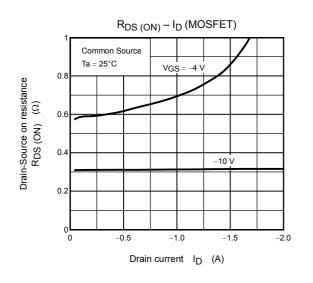
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward voltage	V _{F (1)}	I _F = 0.3 A		0.38	0.45	V
	V _{F (2)}	I _F = 0.5 A	_	0.43	_	V
Reverse current	I _R	V _R = 20 V	_	_	50	μA
Total capacitance	CT	V _R = 0 V, f = 1 MHz	_	46	_	pF

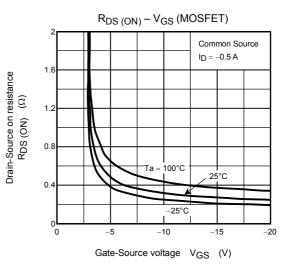
Precaution

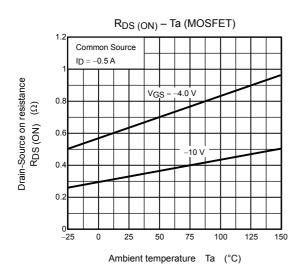
The schottky barrier diode of this product are having large-reverse-current-leakage characteristic compare to the other switching diodes. This current leakage and not proper operating temperature or voltage may cause thermal runaway. Please take forward and reverse loss into consideration when you design.

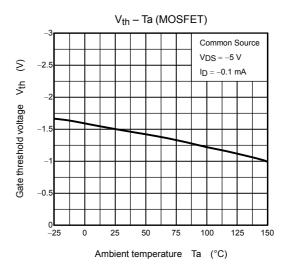










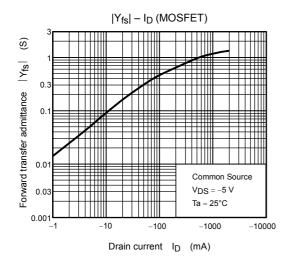


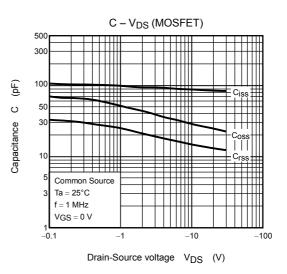
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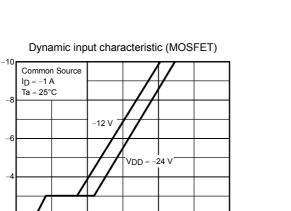
Gate-Source voltage VGS

0

0



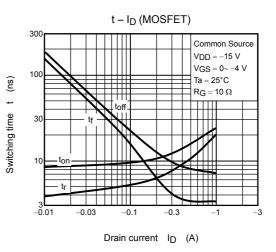


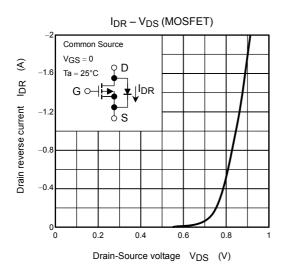


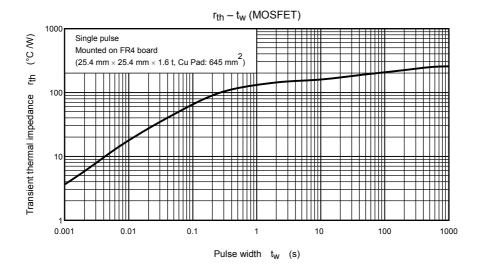
2

Total gate charge Qg (nC)

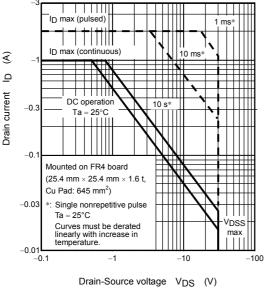
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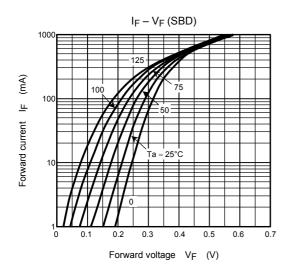


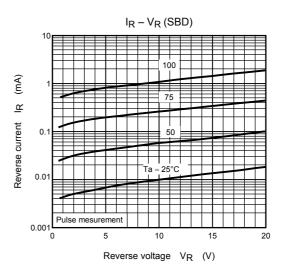


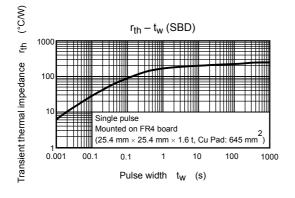
Safe operating area (MOSFET)

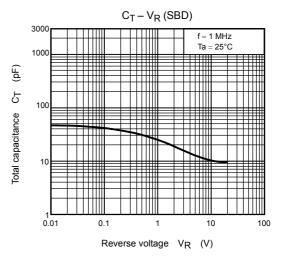


P_D – Ta (MOSFET) 1.2 Mounted on FR4 board Ś (25.4 mm \times 25.4 mm \times 1.6 t, Cu Pad: 645 mm²) PD $t = 10 \ s$ 0.8 Drain power dissipation 0.6 DC 0.4 0.2 0 0 150 50 100 Ambient temperature Ta (°C)









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